IC41C82052 IC41LV82052



2M x 8 (16-MBIT) DYNAMIC RAM WITH FAST PAGE MODE

FEATURES

- · FAST Page Mode access cycle
- TTL compatible inputs and outputs
- · Refresh Interval:
 - -- 2,048 cycles/32 ms
- Refresh Mode: RAS-Only, CAS-before-RAS (CBR), and Hidden
- · JEDEC standard pinout
- Single power supply: 5V±10% or 3.3V ± 10%
- Byte Write and Byte Read operation via CAS

DESCRIPTION

The *ICSI*82052 Series is a 2,097,152 x 8-bit high-performance CMOS Dynamic Random Access Memory. The Fast Page Mode allows 2,048 random accesses within a single row with access cycle time as short as 20 ns per 8-bit word.

These features make the 82052 Series ideally suited for high-bandwidth graphics, digital signal processing, high-performance computing systems, and peripheral applications.

The 82052 Series is packaged in a 28-pin 300mil SOJ and a 28 pin TSOP-2

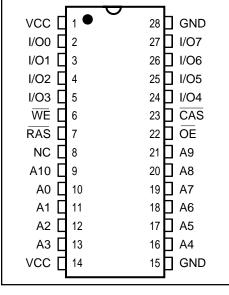
PRODUCT SERIES OVERVIEW

Part No.	Refresh	Voltage
IC41C82052	2K	5V ± 10%
IC41LV82052	2K	3.3V ± 10%

KEY TIMING PARAMETERS

Parameter	-50	-60	Unit
RAS Access Time (trac)	50	60	ns
CAS Access Time (tcac)	13	15	ns
Column Address Access Time (taa)	25	30	ns
EDO Page Mode Cycle Time (tpc)	20	25	ns
Read/Write Cycle Time (tnc)	84	104	ns

PIN CONFIGURATION 28 Pin SOJ, TSOP-2



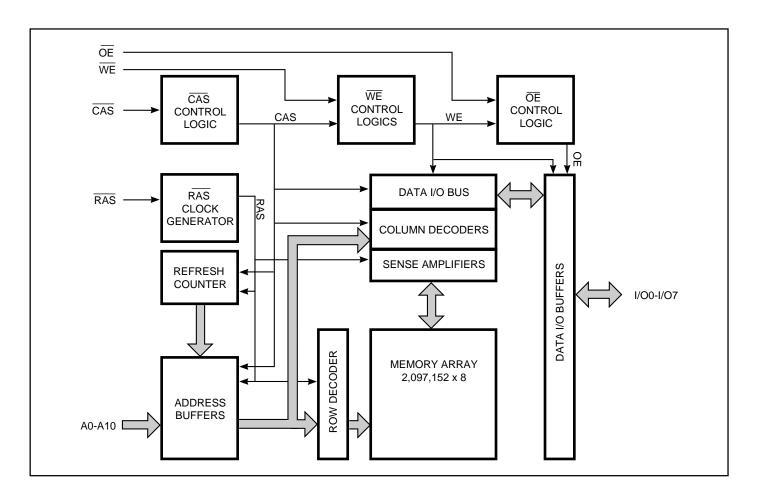
PIN DESCRIPTIONS

A0-A10	Address Inputs
1/00-7	Data Inputs/Outputs
WE	Write Enable
ŌĒ	Output Enable
RAS	Row Address Strobe
CAS	Column Address Strobe
Vcc	Power
GND	Ground
NC	No Connection

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FUNCTIONAL BLOCK DIAGRAM



TRUTH TABLE

Function		RAS	CAS	WE	ŌĒ	Address tr/tc	I/O
Standby		Н	Н	Х	Х	Х	High-Z
Read		L	L	Н	L	ROW/COL	Dout
Write: Word (Early Write)		L	L	L	Χ	ROW/COL	Din
Read-Write		L	L	$H{ ightarrow} L$	$L{\rightarrow}H$	ROW/COL	Dout, DIN
Hidden Refresh	Read	$L{\rightarrow}H{\rightarrow}L$	L	Н	L	ROW/COL	Douт
	Write ⁽¹⁾	$L{\rightarrow}H{\rightarrow}L$	L	L	Χ	ROW/COL	Douт
RAS-Only Refresh		L	Н	Χ	Χ	ROW/NA	High-Z
CBR Refresh		H→L	L	X	Х	Х	High-Z

Note:

1. EARLY WRITE only.



Functional Description

The IC41C82052 and IC41LV82052 are CMOS DRAMs optimized for high-speed bandwidth, low power applications. During READ or WRITE cycles, each bit is uniquely addressed through the 11 address bits. These are entered 11 bits (A0-A10) at a time for the 2K refresh device. The row address is latched by the Row Address Strobe (\overline{RAS}). The column address is latched by the Column Address Strobe (\overline{CAS}). \overline{RAS} is used to latch the first nine bits and \overline{CAS} is used the latter ten bits.

Memory Cycle

A memory cycle is initiated by bring RAS LOW and it is terminated by returning both RAS and CAS HIGH. To ensures proper device operation and data integrity any memory cycle, once initiated, must not be ended or aborted before the minimum tras time has expired. A new cycle must not be initiated until the minimum precharge time trap, top has elapsed.

Read Cycle

A read cycle is initiated by the falling edge of \overline{CAS} or \overline{OE} , whichever occurs last, while holding \overline{WE} HIGH. The column address must be held for a minimum time specified by tar. Data Out becomes valid only when trac, taa, tcac and toea are all satisfied. As a result, the access time is dependent on the timing relationships between these parameters.

Write Cycle

A write cycle is initiated by the falling edge of \overline{CAS} and \overline{WE} , whichever occurs last. The input data must be valid at or before the falling edge of \overline{CAS} or \overline{WE} , whichever occurs last.

Refresh Cycle

To retain data, 2,048 refresh cycles are required in each 32 ms period. There are two ways to refresh the memory:

- By clocking each of the 2,048 row addresses (A0 through A10) with RAS at least once every 32 ms. Any read, write, read-modify-write or RAS-only cycle refreshes the addressed row.
- 2. <u>Using a CAS-before-RAS</u> refresh cycle. <u>CAS-before-RAS</u> refresh is activated by the falling edge of RAS, while holding CAS LOW. In CAS-before-RAS refresh cycle, an internal 11-bit counter provides the row addresses and the external address inputs are ignored.

CAS-before-RAS is a refresh-only mode and no data access or device selection is allowed. Thus, the output remains in the High-Z state during the cycle.

Power-On

After application of the Vcc supply, an initial pause of $200 \, \mu s$ is required followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS signal).

During power-on, it is recommended that \overline{RAS} track with Vcc or be held at a valid VIH to avoid current surges.



ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Parameters		Rating	Unit
VT	Voltage on Any Pin Relative to GND	5V	-1.0 to +7.0	V
		3.3V	-0.5 to +4.6	
Vcc	Supply Voltage	5V	-1.0 to +7.0	V
		3.3V	-0.5 to +4.6	
Іоит	Output Current		50	mA
Po	Power Dissipation		1	W
Та	Commercial Operation Temperature		0 to +70	°C
Тѕтс	Storage Temperature		-55 to +125	°C

Note:

RECOMMENDED OPERATING CONDITIONS (Voltages are referenced to GND.)

Symbol	Parameter		Min.	Тур.	Max.	Unit
V cc	Supply Voltage	5V	4.5	5.0	5.5	V
		3.3V	3.0	3.3	3.6	
VIH	Input High Voltage	5V	2.4	_	Vcc + 1.0	V
		3.3V	2.0	_	Vcc + 0.3	
VIL	Input Low Voltage	5V	-1.0	_	0.8	V
		3.3V	-0.3	_	0.8	
Та	Commercial Ambient Temperature		0	_	70	°C

CAPACITANCE(1,2)

Symbol	Parameter	Max.	Unit
CIN1	Input Capacitance: A0-A10	5	рF
CIN2	Input Capacitance: RAS, CAS, WE, OE	7	pF
Сю	Data Input/Output Capacitance: I/O0-I/O7	7	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.

2. Test conditions: T_A = 25°C, f = 1 MHz.

Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



ELECTRICAL CHARACTERISTICS(1)

(Recommended Operating Conditions unless otherwise noted.)

Symbol	Parameter	Test Condition	Speed	Min.	Max.	Unit
lı∟	Input Leakage Current	Any input 0V ≤ VIN ≤ Vcc Other inputs not under test = 0V		– 5	5	μΑ
lio	Output Leakage Current	Output is disabled (Hi-Z) 0V ≤ Vouт ≤ Vcc		– 5	5	μΑ
Vон	Output High Voltage Level	Iон = -5.0 mA with Vcc=5V Iон = -2.0 mA with Vcc=3.3V		2.4	_	V
V OL	Output Low Voltage Level	IoL = 4.2 mA with Vcc=5V IoL = 2 mA with Vcc=3.3V		_	0.4	V
lcc1	Standby Current: TTL	RAS, CAS ≥ VIH	5V 3.3V	_	2 0.5	mA
lcc2	Standby Current: CMOS	RAS, CAS ≥ Vcc – 0.2V	5V 3.3V	_	1 0.5	mA
lcc3	Operating Current: Random Read/Write ^(2,3,4) Average Power Supply Current	RAS, CAS, Address Cycling, tac = tac (min.)	-50 -60	_	120 110	mA
Icc4	Operating Current: Fast Page Mode ^(2,3,4) Average Power Supply Current	$\overline{RAS} = V_{IL}, \overline{CAS},$ $t_{RC} = t_{RC} \text{ (min.)}$	-50 -60	_	90 80	mA
lcc5	Refresh Current: RAS-Only ^(2,3) Average Power Supply Current	RAS Cycling, CAS ≥ VIH tRC = tRC (min.)	-50 -60	_	120 110	mA
lcc6	Refresh Current: CBR ^(2,3,5) Average Power Supply Current	RAS, CAS Cycling trc = trc (min.)	-50 -60		120 110	mA

Notes:

^{1.} An initial pause of 200 μ s is required after power-up followed by eight \overline{RAS} refresh cycles (\overline{RAS} -Only or CBR) before proper device operation is assured. The eight \overline{RAS} cycles wake-up should be repeated any time the tree refresh requirement is exceeded.

^{2.} Dependent on cycle rates.

^{3.} Specified values are obtained with minimum cycle time and the output open.

^{4.} Column-address is changed once each EDO page cycle.

^{5.} Enables on-chip refresh and address counters.



AC CHARACTERISTICS(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

	_		50		30	
Symbol	Parameter	Min.	Max.	Min.	Max.	Units
trc	Random READ or WRITE Cycle Time	84	_	104	_	ns
trac	Access Time from RAS ^(6, 7)	_	50	_	60	ns
tcac	Access Time from CAS (6, 8, 15)	_	13	_	15	ns
taa	Access Time from Column-Address ⁽⁶⁾	_	25	_	30	ns
tras	RAS Pulse Width	50	10K	60	10K	ns
trp	RAS Precharge Time	30	_	40	_	ns
tcas	CAS Pulse Width ⁽²³⁾	8	10K	10	10K	ns
tcp	CAS Precharge Time ⁽⁹⁾	9	_	9	_	ns
tсsн	CAS Hold Time (21)	38	_	40	_	ns
trcd	RAS to CAS Delay Time(10, 20)	12	37	14	45	ns
tasr	Row-Address Setup Time	0	_	0	_	ns
trah	Row-Address Hold Time	7	_	10	_	ns
tasc	Column-Address Setup Time(20)	0	_	0	_	ns
tcah	Column-Address Hold Time(20)	8	_	10	_	ns
tar	Column-Address Hold Time (referenced to RAS)	30	_	40	_	ns
trad	RAS to Column-Address Delay Time(11)	10	25	12	30	ns
tral	Column-Address to RAS Lead Time	25	_	30	_	ns
trpc	RAS to CAS Precharge Time	5	_	5	_	ns
trsh	RAS Hold Time	8	_	10	_	ns
trhcp	RAS Hold Time from CAS Precharge	30	_	35	_	ns
tclz	CAS to Output in Low-Z(15, 24)	0	_	0	_	ns
tcrp	CAS to RAS Precharge Time(21)	5	_	5	_	ns
top	Output Disable Time(19, 24)	3	15	3	15	ns
toe	Output Enable Time(15, 16)	_	12	_	15	ns
toed	Output Enable Data Delay (Write)	12	_	15	_	ns
toehc	OE HIGH Hold Time from CAS HIGH	5	_	5	_	ns
toep	OE HIGH Pulse Width	10	_	10	_	ns
toes	OE LOW to CAS HIGH Setup Time	5	_	5	_	ns
trcs	Read Command Setup Time(17, 20)	0	_	0	_	ns
trrh	Read Command Hold Time (referenced to RAS) ⁽¹²⁾	0	_	0	_	ns
tпсн	Read Command Hold Time (referenced to CAS)(12, 17, 21)	0	_	0	_	ns
twch	Write Command Hold Time(17)	8	_	10	_	ns
twcr	Write Command Hold Time (referenced to RAS) ⁽¹⁷⁾	40	_	50	_	ns
twp	Write Command Pulse Width(17)	8	_	10	_	ns
twpz	WE Pulse Widths to Disable Outputs	7	_	7	_	ns
trwL	Write Command to RAS Lead Time(17)	13	_	15	_	ns
tcwL	Write Command to CAS Lead Time(17, 21)	8	_	10		ns
twcs	Write Command Setup Time ^(14, 17, 20)	0	_	0	_	ns
tohr	Data-in Hold Time (referenced to RAS)	39		39		ns



AC CHARACTERISTICS (Continued)(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

			-50		-60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Units
tach	Column-Address Setup Time to CAS Precharge during WRITE Cycle	15	_	15	_	ns
tоен	OE Hold Time from WE during READ-MODIFY-WRITE cycle ⁽¹⁸⁾	8	_	10	_	ns
tos	Data-In Setup Time(15, 22)	0	_	0	_	ns
tон	Data-In Hold Time(15, 22)	8	_	10	_	ns
trwc	READ-MODIFY-WRITE Cycle Time	108	_	133	_	ns
trwd	RAS to WE Delay Time during READ-MODIFY-WRITE Cycle(14)	64	_	77	_	ns
tcwp	CAS to WE Delay Time(14, 20)	26	_	32	_	ns
tawd	Column-Address to WE Delay Time(14)	39	_	47	_	ns
tpc	EDO Page Mode READ or WRITE Cycle Time	20	_	25	_	ns
trasp	RAS Pulse Width in EDO Page Mode	50	100K	60	100K	ns
tcpa	Access Time from CAS Precharge(15)	_	30	_	35	ns
tprwc	EDO Page Mode READ-WRITE Cycle Time	56	_	68	_	ns
tсон	Data Output Hold after CAS LOW	5	_	5	_	ns
toff	Output Buffer Turn-Off Delay from CAS or RAS(13,15,19,24)	0	12	0	15	ns
twnz	Output Disable Delay from WE	3	10	3	10	ns
tcsr	CAS Setup Time (CBR REFRESH)(20, 25)	5	_	5	_	ns
tchr	CAS Hold Time (CBR REFRESH)(21, 25)	8	_	10	_	ns
tord	OE Setup Time prior to RAS during HIDDEN REFRESH Cycle	0	_	0	_	ns
tref	Auto Refresh Period 2,048 Cycles	_	32	_	32	ms
tτ	Transition Time (Rise or Fall)(2,3)	50	1	50	ns	

AC TEST CONDITIONS

Output load: Two TTL Loads and 50 pF (Vcc = $5.0V \pm 10\%$)

One TTL Load and 50 pF (Vcc = $3.3V \pm 10\%$)

Input timing reference levels: $V_{IH} = 2.4V$, $V_{IL} = 0.8V$ (Vcc = $5.0V \pm 10\%$)

 $V_{IH} = 2.0V$, $V_{IL} = 0.8V$ ($V_{CC} = 3.3V \pm 10\%$)

Output timing reference levels: VoH = 2.0V, VoL = 0.8V (Vcc = $5.0V \pm 10\%$, $3.3V \pm 10\%$)

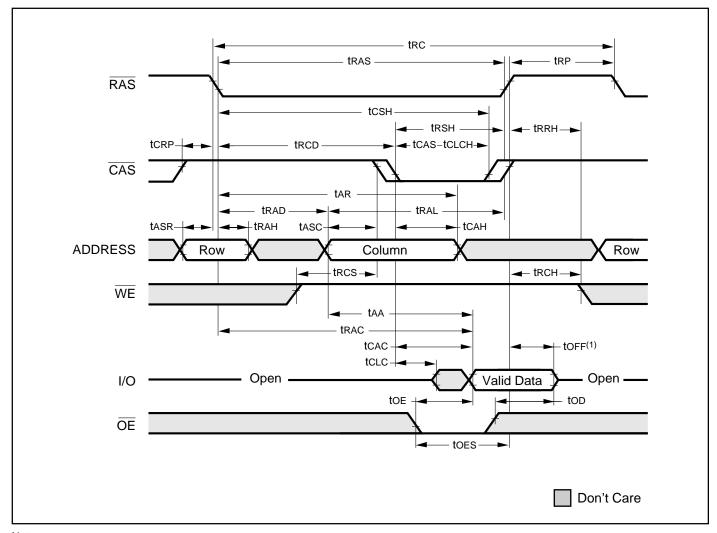


Notes:

- 1. An initial pause of 200 μ s is required after power-up followed by eight \overline{RAS} refresh cycle (\overline{RAS} -Only or CBR) before proper device operation is assured. The eight \overline{RAS} cycles wake-up should be repeated any time the tree refresh requirement is exceeded.
- 2. V_{IH} (MIN) and V_{IL} (MAX) are reference levels for measuring timing of input signals. Transition times, are measured between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) and assume to be 1 ns for all inputs.
- 3. In addition to meeting the transition rate specification, all input signals must transit between V_IH and V_IL (or between V_IL and V_IH) in a monotonic manner.
- 4. If \overline{CAS} and $\overline{RAS} = V_{IH}$, data output is High-Z.
- 5. If $\overline{CAS} = V_{IL}$, data output may contain data from the last valid READ cycle.
- 6. Measured with a load equivalent to one TTL gate and 50 pF.
- 7. Assumes that tRCD ≤ tRCD (MAX). If tRCD is greater than the maximum recommended value shown in this table, tRAC will increase by the amount that tRCD exceeds the value shown.
- 8. Assumes that $trcd \ge trcd$ (MAX).
- 9. If $\overline{\text{CAS}}$ is LOW at the falling edge of $\overline{\text{RAS}}$, data out will be maintained from the previous cycle. To initiate a new cycle and clear the data output buffer, $\overline{\text{CAS}}$ and $\overline{\text{RAS}}$ must be pulsed for tcp.
- 10. Operation with the trop (MAX) limit ensures that trac (MAX) can be met. trop (MAX) is specified as a reference point only; if trop is greater than the specified trop (MAX) limit, access time is controlled exclusively by toac.
- 11. Operation within the trad (MAX) limit ensures that trad (MAX) can be met. trad (MAX) is specified as a reference point only; if trad is greater than the specified trad (MAX) limit, access time is controlled exclusively by trad.
- 12. Either trich or trich must be satisfied for a READ cycle.
- 13. toff (MAX) defines the time at which the output achieves the open circuit condition; it is not a reference to Voh or Vol.
- 14. twcs, trwb, tawb and tcwb are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycle only. If twcs ≥ twcs (MIN), the cycle is an EARLY WRITE cycle and the data output will remain open circuit throughout the entire cycle. If trwb ≥ trwb (MIN), tawb ≥ tawb (MIN) and tcwb ≥ tcwb (MIN), the cycle is a READ-WRITE cycle and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until CAS and RAS or OE go back to Vih) is indeterminate. OE held HIGH and WE taken LOW after CAS goes LOW result in a LATE WRITE (OE-controlled) cycle.
- 15. Output parameter (I/O) is referenced to corresponding CAS input.
- 16. During a READ cycle, if \overline{OE} is LOW then taken HIGH before \overline{CAS} goes HIGH, I/O goes open. If \overline{OE} is tied permanently LOW, a LATE WRITE or READ-MODIFY-WRITE is not possible.
- 17. Write command is defined as \overline{WE} going low.
- 18. LATE WRITE and READ-MODIFY-WRITE cycles must have both top and toeh met (OE HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The I/Os will provide the previously written data if CAS remains LOW and OE is taken back to LOW after toeh is met.
- 19. The I/Os are in open during READ cycles once top or toff occur.
- 20. Determined by falling edge of CAS.
- 21. Determined by rising edge of CAS.
- 22. These parameters are referenced to $\overline{\text{CAS}}$ leading edge in EARLY WRITE cycles and $\overline{\text{WE}}$ leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
- 23. CAS must meet minimum pulse width.
- 24. The 3 ns minimum is a parameter guaranteed by design.
- 25. Enables on-chip refresh and address counters.



READ CYCLE

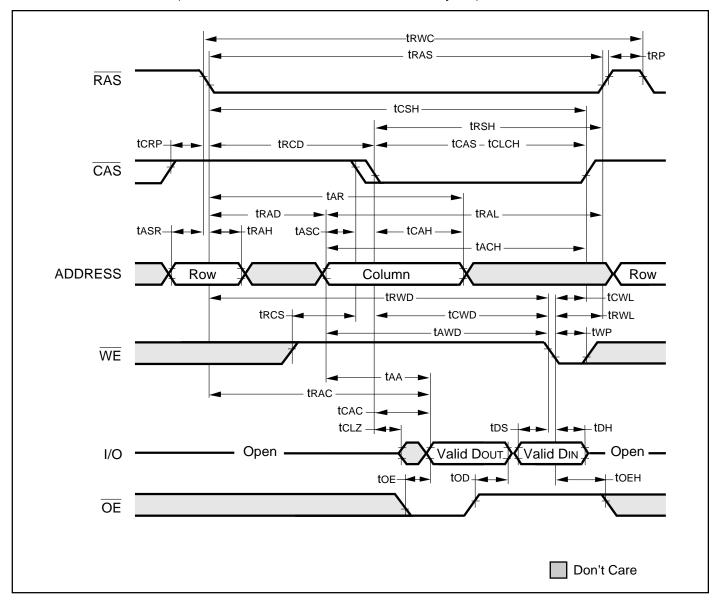


Note:

1. toff is referenced from rising edge of $\overline{\mbox{RAS}}$ or $\overline{\mbox{CAS}},$ whichever occurs last.

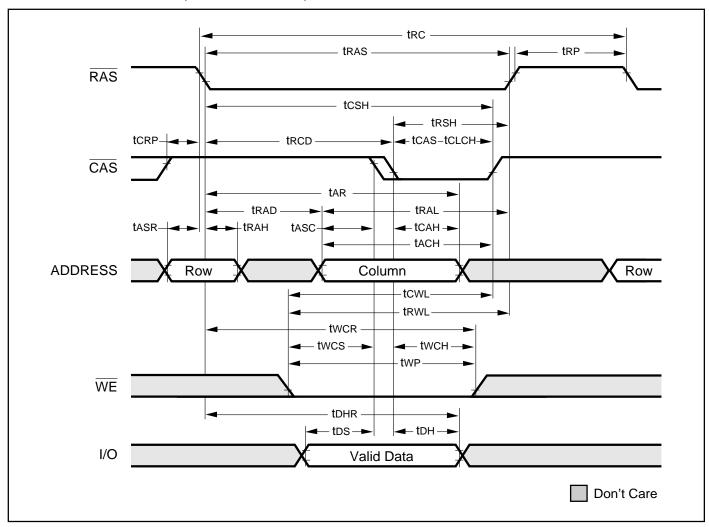


READ WRITE CYCLE (LATE WRITE and READ-MODIFY-WRITE Cycles)



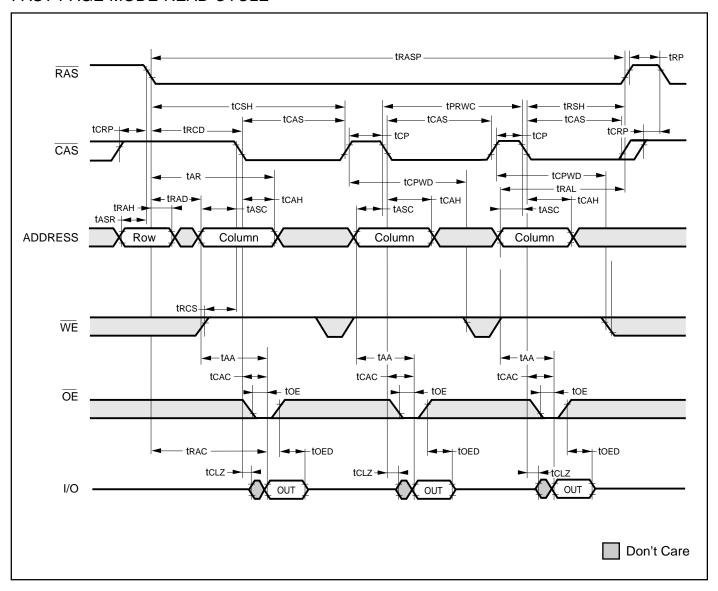


EARLY WRITE CYCLE (OE = DON'T CARE)



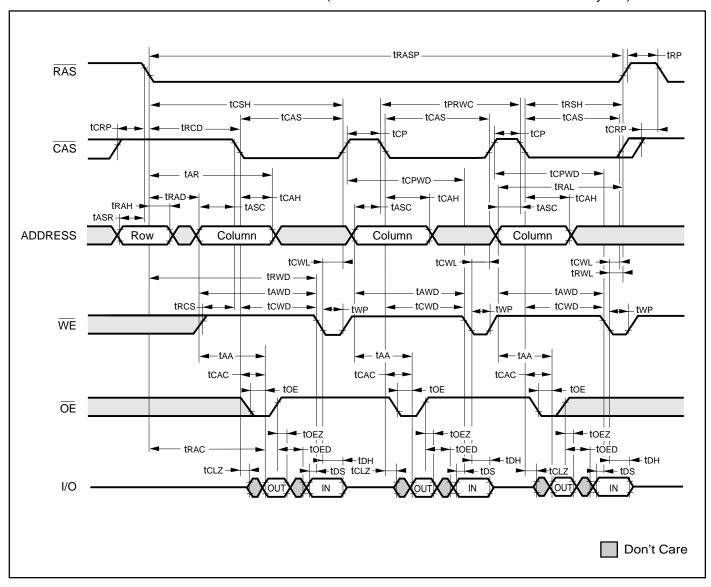


FAST PAGE MODE READ CYCLE



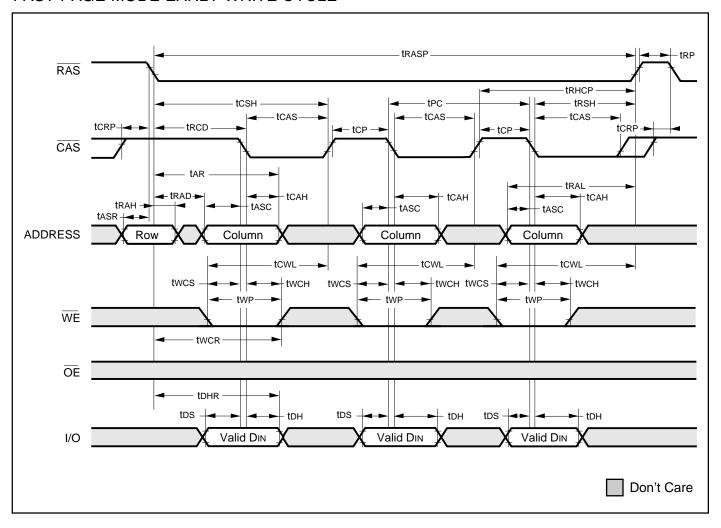


FAST PAGE MODE READ WRITE CYCLE (LATE WRITE and READ-MODIFY-WRITE Cycles)





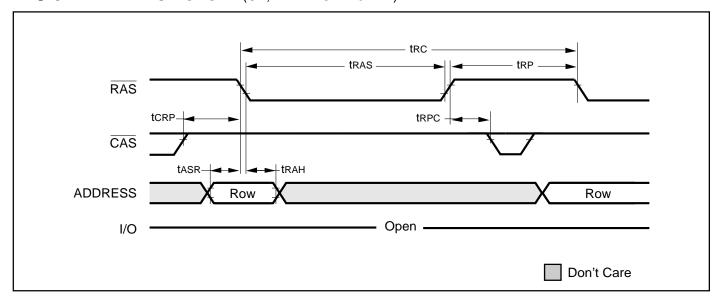
FAST PAGE MODE EARLY WRITE CYCLE





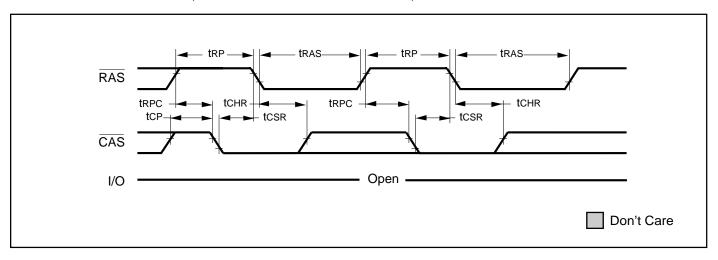
AC WAVEFORMS

RAS-ONLY REFRESH CYCLE (OE, WE = DON'T CARE)

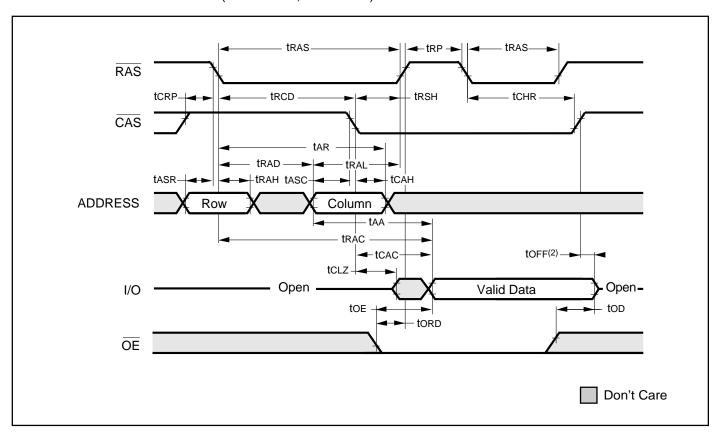




CBR REFRESH CYCLE (Addresses; WE, OE = DON'T CARE)



HIDDEN REFRESH CYCLE (WE = HIGH; OE = LOW)





ORDERING INFORMATION

Commercial Range: 0°C to 70°C

Voltage: 5V

Speed (ns)	Order Part No.	Refresh	Package
50	IC41C82052-50J	2K	300mil SOJ
50	IC41C82052-50T	2K	400mil TSOP-2
60	IC41C82052-60J	2K	300mil SOJ
60	IC41C82052-60T	2K	400mil TSOP-2

Voltage: 3.3V

Speed (ns)	Order Part No.	Refresh	Package
50	IC41LV82052-50J	2K	300mil SOJ
50	IC41LV82052-50T	2K	400mil TSOP-2
60	IC41LV82052-60J	2K	300mil SOJ
60	IC41LV82052-60T	2K	400mil TSOP-2





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